STEIFPOWER TECHNOLOGY

40V N+P Dual Channel MOSFETs

SPC4756T

General Description

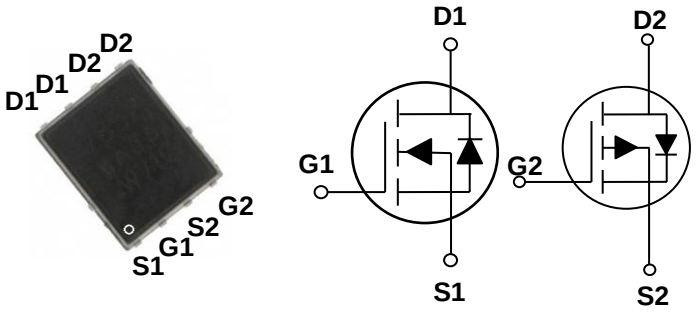
These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
40V	11.5mΩ	42A
-40V	30mΩ	-27A

Features

- *Fast switching*
- *Green Device Available*
- *Suit for 4.5V Gate Drive Applications*
- *100% EAS Guaranteed*

PPAK5x6 Dual Pin Configuration



Applications

- *DC Fan*
- *Motor Drive Applications*
- *Networking*
- *Half / Full Bridge Topology*

RoHS COMPLIANT

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating		Units
V_{DS}	Drain-Source Voltage	40	-40	V
V_{GS}	Gate-Source Voltage	±20	±20	V
I_D	Drain Current – Continuous (T_C=25℃)	42	-27	A
	Drain Current – Continuous (T_C=100℃)	26.5	-17	A
I_{DM}	Drain Current – Pulsed[1]	168	-108	A
EAS	Single Pulse Avalanche Energy[2,6]	45	51	mJ
IAS	Single Pulse Avalanched Current[2]	30	32	A
P_D	Power Dissipation (T_C=25℃)	34.7		W
	Power Dissipation – Derate above 25℃	0.28		W/℃
T_{STG}	Storage Temperature Range	-55 to 150		℃
T_J	Operating Junction Temperature Range	-55 to 150		℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	3.6	℃/W

N-CH Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	40	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.04	---	V/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=40V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=32V , V_{GS}=0V , T_J=125℃	---	---	10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V , I_D=15A	---	9.7	11.5	mΩ
		V_{GS}=4.5V , I_D=12A	---	12.5	16	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4.9	---	mV/℃
gfs	Forward Transconductance	V_{DS}=10V , I_D=3A	---	6	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge[3,4]	V_{DS}=20V , V_{GS}=10V , I_D=10A	---	16.9	32	nC
Q_{gs}	Gate-Source Charge[3,4]		---	2	4	
Q_{gd}	Gate-Drain Charge[3,4]		---	4.4	9	
$T_{d(on)}$	Turn-On Delay Time[3,4]	V_{DD}=20V , V_{GS}=10V , R_G=6Ω I_D=1A	---	8	16	ns
T_r	Rise Time[3,4]		---	3.2	8	
$T_{d(off)}$	Turn-Off Delay Time[3,4]		---	26.4	52	
T_f	Fall Time[3,4]		---	3.8	8	
C_{iss}	Input Capacitance	V_{DS}=20V , V_{GS}=0V , F=1MHz	---	1109	2200	pF
C_{oss}	Output Capacitance		---	114	220	
C_{rss}	Reverse Transfer Capacitance		---	89	180	
Rg	Gate resistance	V_{GS}=0V, V_{DS}=0V, F=1MHz	---	2.8	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	42	A
I_{SM}	Pulsed Source Current		---	---	84	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=30A.,R_G=25Ω, Starting T_J=25℃.
3. The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
4. Essentially independent of operating temperature.

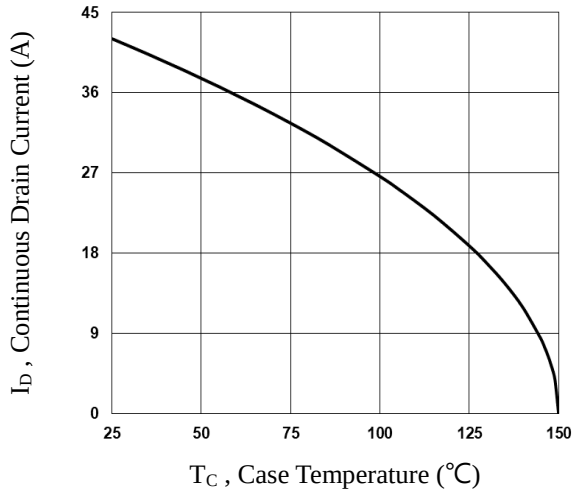


Fig.1 Continuous Drain Current vs. T_C

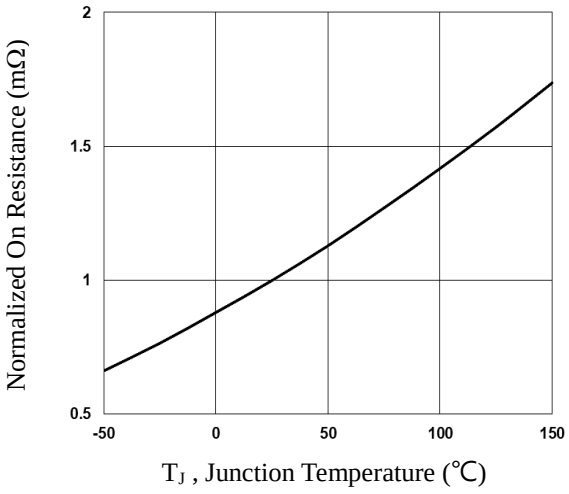


Fig.2 Normalized RDSON vs. T_J

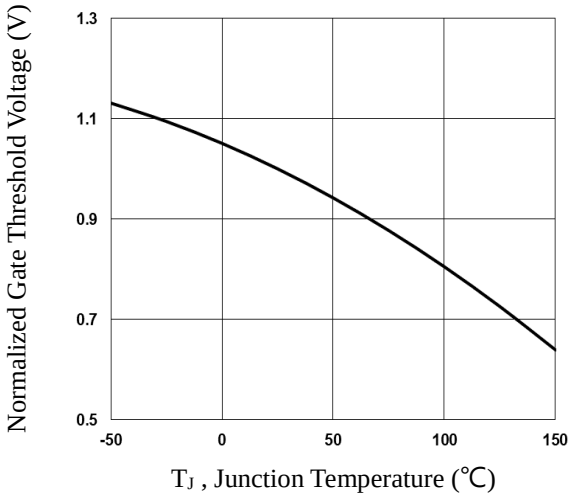


Fig.3 Normalized V_{th} vs. T_J

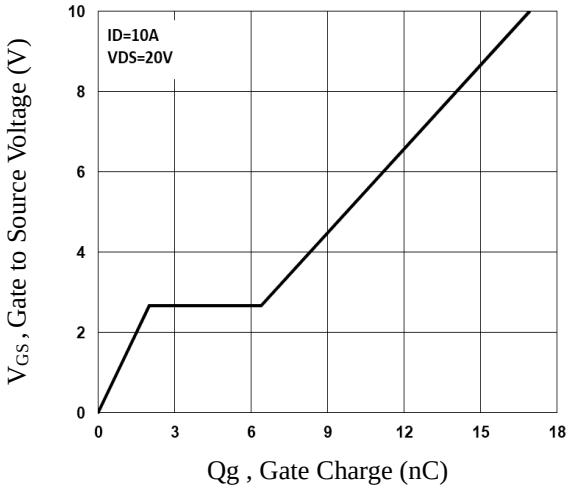


Fig.4 Gate Charge Waveform

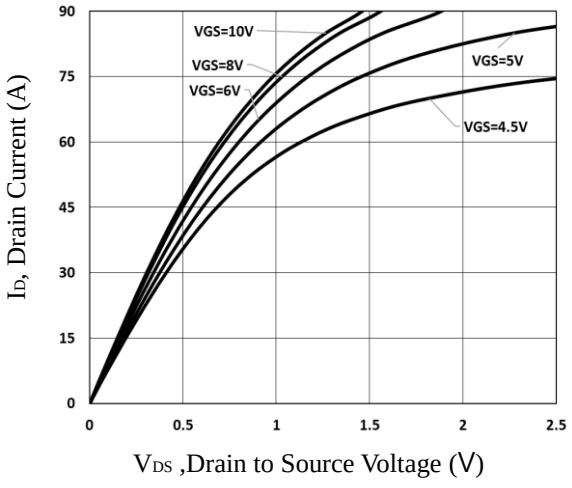


Fig.5 Typical Output Characteristics

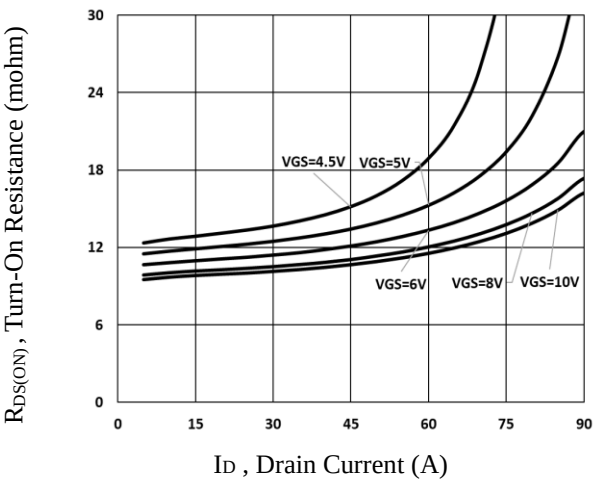


Fig.6 Turn-On Resistance vs. ID

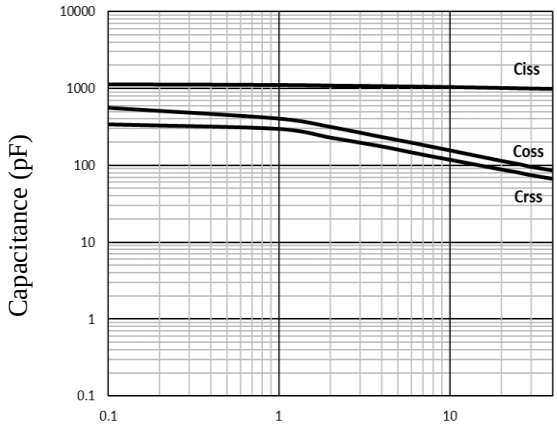


Fig.7 Capacitance Characteristics

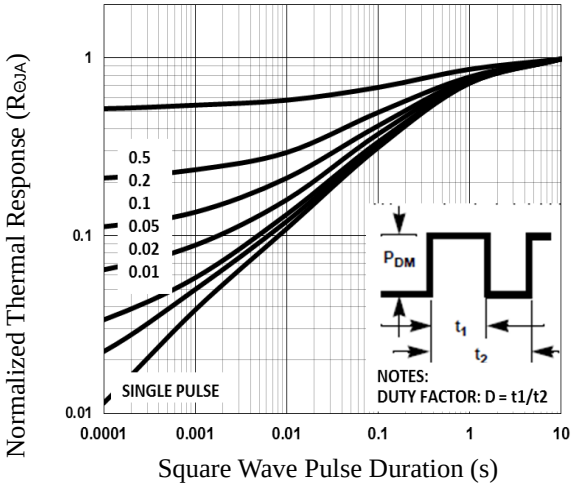


Fig.8 Normalized Transient Response

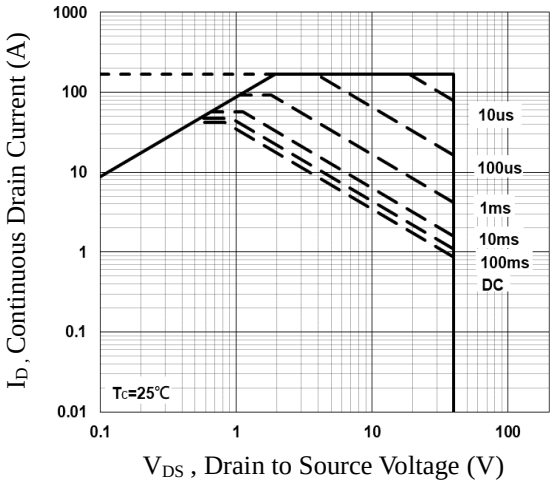


Fig.9 Maximum Safe Operation Area

P-CH Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=-250uA	-40	---	---	V
△BV_{DSS}/△T_J	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=-1mA	---	0.02	---	V/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=-40V , V_{GS}=0V , T_J=25℃	---	---	-1	uA
		V_{DS}=-32V , V_{GS}=0V , T_J=125℃	---	---	-10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=-10V , I_D=-10A	---	25	30	mΩ
		V_{GS}=-4.5V , I_D=-8A	---	35	45	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =-250uA	-1.2	-1.5	-2.5	V
△$V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4.4	---	mV/℃
gfs	Forward Transconductance	V_{DS}=-10V , I_D=-3A	---	6	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge[7,8]	V_{DS}=-20V , V_{GS}=-10V , I_D=-10A	---	23.2	46	nC
Q_{gs}	Gate-Source Charge[7,8]		---	2.9	6	
Q_{gd}	Gate-Drain Charge[7,8]		---	4.3	8.6	
$T_{d(on)}$	Turn-On Delay Time[7,8]	V_{DD}=-20V , V_{GS}=-10V , R_G=6Ω I_D=-1A	---	12.8	25	ns
T_r	Rise Time[7,8]		---	8.7	18	
$T_{d(off)}$	Turn-Off Delay Time[7,8]		---	65	120	
T_f	Fall Time[7,8]		---	12.6	25	
C_{iss}	Input Capacitance	V_{DS}=-20V , V_{GS}=0V , F=1MHz	---	1320	2600	pF
C_{oss}	Output Capacitance		---	116	230	
C_{rss}	Reverse Transfer Capacitance		---	89	180	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	-27	A
I_{SM}	Pulsed Source Current		---	---	-54	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=-1A , T_J=25℃	---	---	-1	V

Note :

5. Repetitive Rating : Pulsed width limited by maximum junction temperature.
6. V_{DD}=-25V,V_{GS}=-10V,L=0.1mH,I_{AS}=-32A.,R_G=25Ω, Starting T_J=25℃
7. The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
8. Essentially independent of operating temperature.

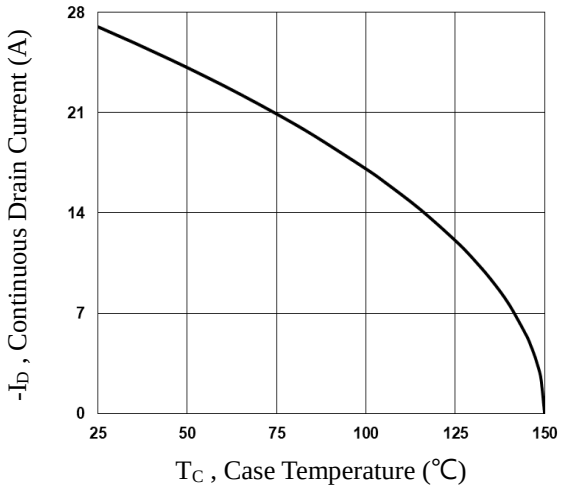


Fig.10 Continuous Drain Current vs. T_C

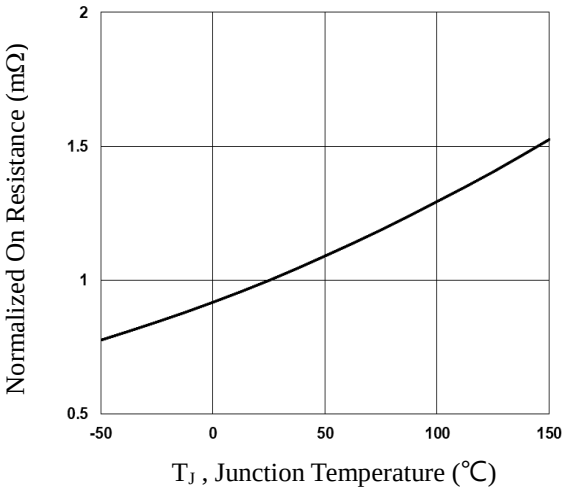


Fig.11 Normalized RDSON vs. T_J

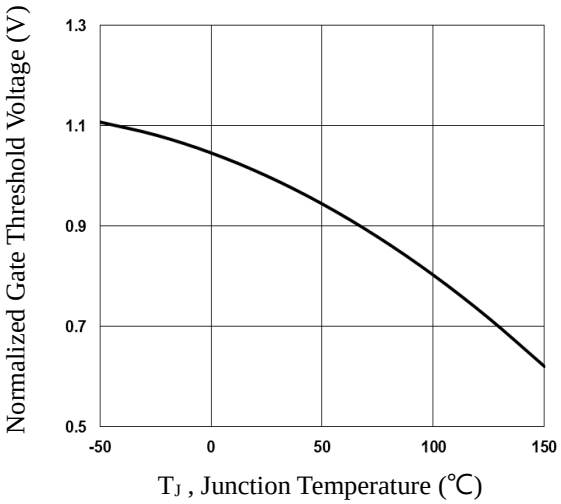


Fig.12 Normalized V_{th} vs. T_J

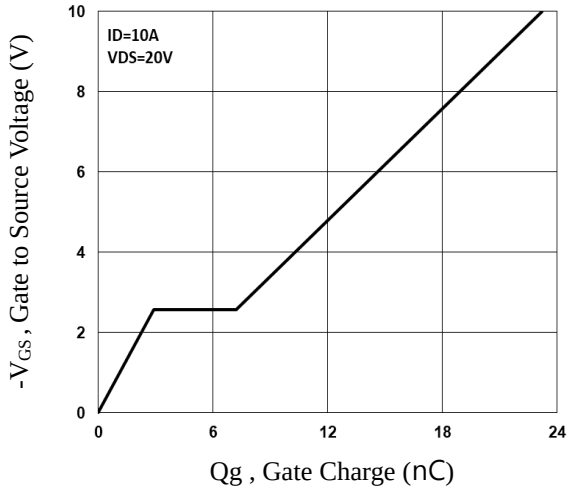


Fig.13 Gate Charge Waveform

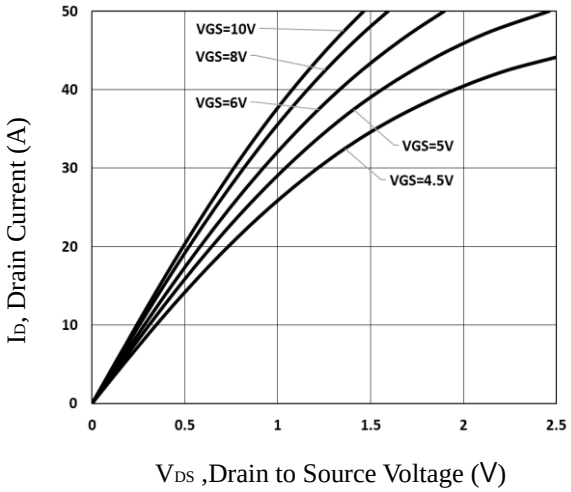


Fig.14 Typical Output Characteristics

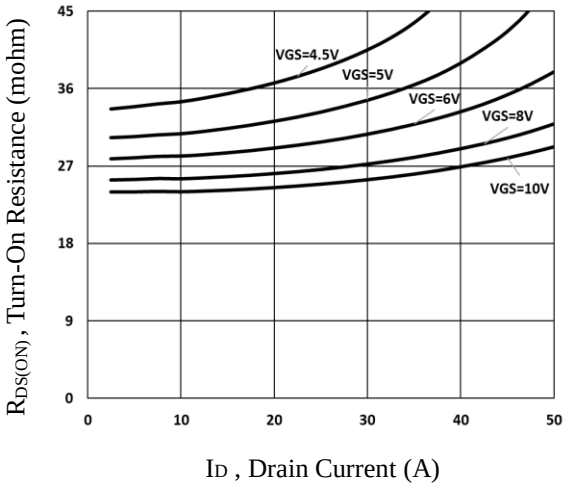


Fig.15 Turn-On Resistance vs. I_D

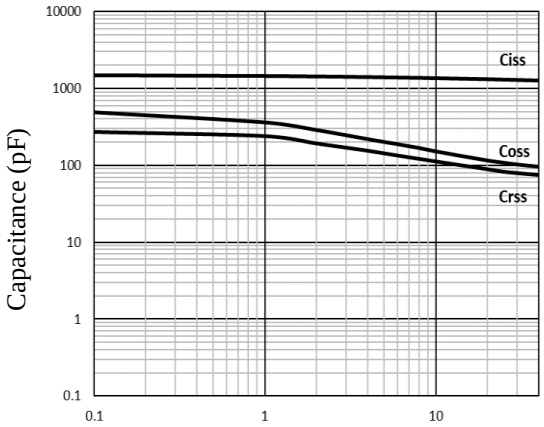


Fig.16 Capacitance Characteristics

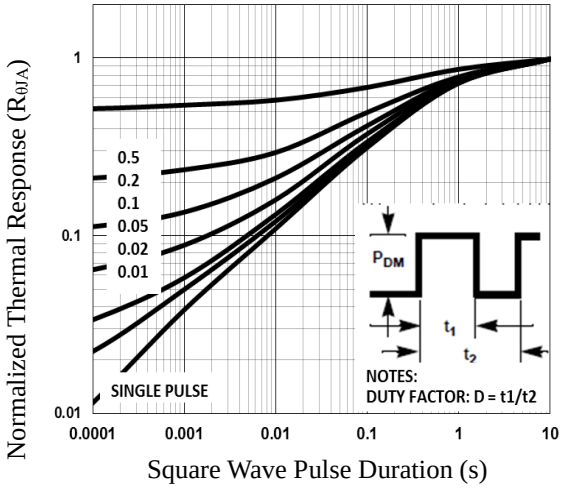


Fig.17 Normalized Transient Impedance

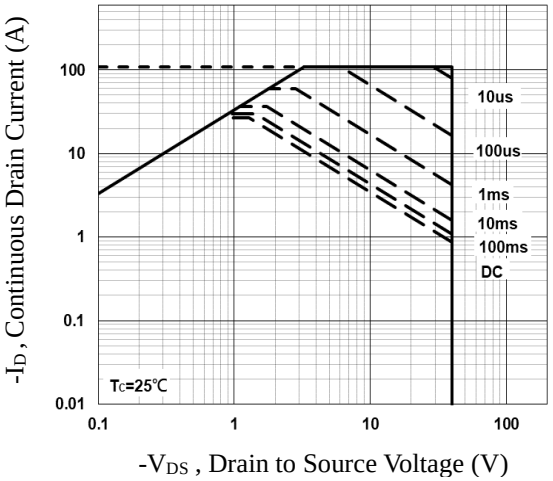
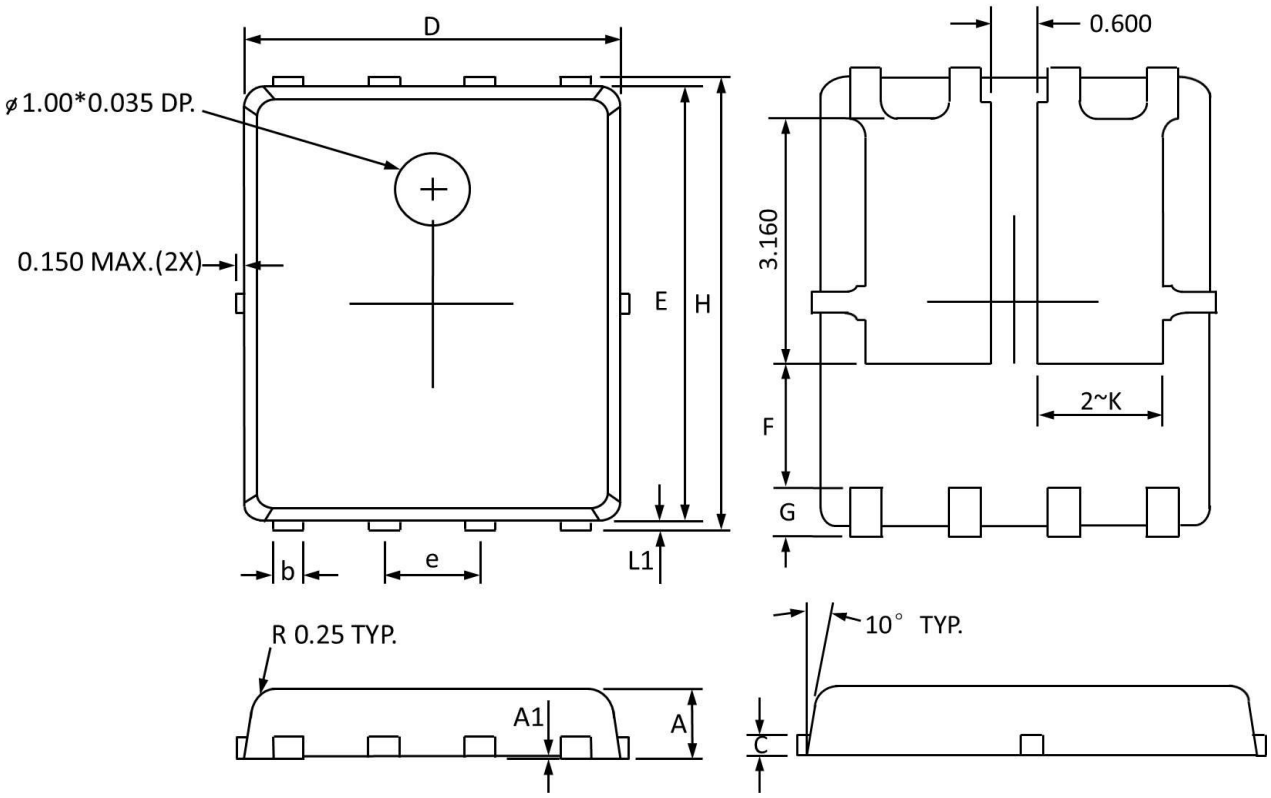


Fig.18 Maximum Safe Operation Area

PPAK5x6 Dual PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.800	1.000	0.032	0.039
A1	0.000	0.005	0.000	0.000
b	0.350	0.490	0.014	0.019
C	0.254 Ref		0.254 Ref	
D	4.900	5.100	0.193	0.200
E	5.700	5.900	0.225	0.232
e	1.27 BSC		1.27 BSC	
F	1.600 Ref		1.600 Ref	
G	0.600 Ref		0.600 Ref	
H	5.950	6.200	0.235	0.244
L1	0.100	0.180	0.004	0.007
K	1.600 Ref		1.600 Ref	